

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2672372

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>CHING-FENG FU</td> <td>12/12/2013</td> </tr> <tr> <td>DE-FANG CHEN</td> <td>12/13/2013</td> </tr> <tr> <td>CHUN-HUNG LEE</td> <td>12/13/2013</td> </tr> <tr> <td>HUAN-JUST LIN</td> <td>12/12/2013</td> </tr> <tr> <td>HUI-CHENG CHANG</td> <td>12/13/2013</td> </tr> </tbody> </table>		Name	Execution Date	CHING-FENG FU	12/12/2013	DE-FANG CHEN	12/13/2013	CHUN-HUNG LEE	12/13/2013	HUAN-JUST LIN	12/12/2013	HUI-CHENG CHANG	12/13/2013
Name	Execution Date												
CHING-FENG FU	12/12/2013												
DE-FANG CHEN	12/13/2013												
CHUN-HUNG LEE	12/13/2013												
HUAN-JUST LIN	12/12/2013												
HUI-CHENG CHANG	12/13/2013												
RECEIVING PARTY DATA													
<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED</td> </tr> <tr> <td>Street Address:</td> <td>NO. 8, LI-HSIN ROAD, VI</td> </tr> <tr> <td>Internal Address:</td> <td>HSINCHU SCIENCE PARK</td> </tr> <tr> <td>City:</td> <td>HSINCHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED	Street Address:	NO. 8, LI-HSIN ROAD, VI	Internal Address:	HSINCHU SCIENCE PARK	City:	HSINCHU	State/Country:	TAIWAN		
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED												
Street Address:	NO. 8, LI-HSIN ROAD, VI												
Internal Address:	HSINCHU SCIENCE PARK												
City:	HSINCHU												
State/Country:	TAIWAN												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14150177</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14150177								
Property Type	Number												
Application Number:	14150177												
CORRESPONDENCE DATA													
<p>Fax Number: (212)755-7306</p> <p>Phone: 212-326-3939</p> <p>Email: erosenfelder@JonesDay.com</p> <p><i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i></p> <p>Correspondent Name: JONES DAY</p> <p>Address Line 1: 222 EAST 41ST ST</p> <p>Address Line 4: NEW YORK, NEW YORK 10017</p>													
ATTORNEY DOCKET NUMBER:	181877-625060												
NAME OF SUBMITTER:	MATTHEW W. JOHNSON												

Signature:	/Matthew W. Johnson/
Date:	01/08/2014
Total Attachments: 2 source=625060_Assignment#page1.tif source=625060_Assignment#page2.tif	

ASSIGNMENT

WHEREAS, WE, CHING-FENG FU, DE-FANG CHEN, CHUN-HUNG LEE, HUAN-JUST LIN and HUI-CHENG CHANG citizen of the Republic of China, having the mailing addresses listed as below.

CHING-FENG FU having a mailing address of No. 14-2, Ln. 248, Xueshi Rd., North Dist., Taichung City 404, Taiwan residing at Taichung City, Taiwan;

DE-FANG CHEN having a mailing address of 6F.-1, No. 375, Sec. 2, Gongdao 5th Rd., East Dist., Hsinchu City 300, Taiwan residing at Hsinchu City, Taiwan;

CHUN-HUNG LEE having a mailing address of 7F., No. 470, Puding 1st Rd., East Dist., Hsinchu City 300, Taiwan residing at Hsinchu City, Taiwan;

HUAN-JUST LIN having a mailing address of No. 126, Lane 228, Wuling Rd., Hsinchu City 300, Taiwan residing at Hsinchu City, Taiwan;

HUI-CHENG CHANG having a mailing address of No. 11, Ln. 220, Xinglong St., Guantian Dist., Tainan City 720, Taiwan residing at Tainan City, Taiwan,

ASSIGNORS, are the inventors of the invention in "METHOD OF FORMING CHANNEL OF GATE STRUCTURE" for which we have executed an application for a Patent of the United States

- ☒ which is executed on ☒ even date herewith or ☐
☒ which is identified by Jones Day docket no. 181877-625060
☐ which was filed on December _____, 2013, Application No. _____
☐ We hereby authorize and request attorney(s) at Jones Day, to insert here in parentheses (Application number _____, filed _____) the filing date and application number of said application when known.

and WHEREAS, Taiwan Semiconductor Manufacturing Company Limited, a corporation organized and existing under the laws of Republic of China, and having an office for the transaction of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu, Taiwan, ASSIGNEE, is desirous of obtaining our entire right, title and interest in, to and under the said invention and the said application:

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, we, the said ASSIGNORS, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, our entire right, title and interest in, to and under the said invention, and the said United States application and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said United States application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and all right to sue for infringement including past infringement.

AND WE HEREBY authorize and request the Commissioner for Patents and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant and agree that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

IN TESTIMONY WHEREOF, We hereunto set our hands and seals the day and year set opposite our respective signatures.

✓ Date 12, 12, 2013

✓ CHING-FENG FU L.S.
CHING-FENG FU

✓ Date 12, 13, 2013

✓ De-Fang Chen L.S.
DE-FANG CHEN

✓ Date 12. 13, 2013

✓ Chun-Hung Lee L.S.
CHUN-HUNG LEE

✓ Date 12. 12, 2013

✓ HUAN-JUST LIN L.S.
HUAN-JUST LIN

✓ Date 12/13/13, 2013

✓ Hui-Cheng Chang L.S.
HUI-CHENG CHANG